



Sabine Lange Detector Group DESY

Medipix meeting, May 29-31, 2012





Lambda project

About Lambda:

- 2 x 6 Medipix3 chips (~28 x 85mm)
- high frame rate (8 read out lines, 2kHz readout)
- 10 gigabit Ethernet high-speed readout
- experiments up to 100 keV (high-Z sensors)





Sabine Lange | Lambda | May 29-31, 2012 | Page 2



Folie 2

New sensor production

Development of readout system and mechanics

Ideas for TSV-compatible board development



Large-area silicon sensors

2 x 6 – chip layout Si, 55µm pitch, 300µm thick (2/6 received)

- Ordered from Canberra delayed, opted for 5" wafer instead of 6"
- Bonded at IZM no problems reported with planarity, etc.
- X-ray tests at IZM show a small number of joined bumps on 2 chips of 1 module (other module OK)





Germanium sensors

55µm pitch Ge sensors produced by Canberra (Lingolsheim)

2 x 90mm wafers with single Medipix3 sensors

Indium bump bonding at IZM

- Processing conditions optimised to avoid damage to Ge & bump height tested
- Currently bonding HPGe sensors to Medipix3





New sensor production

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Lambda project

Lambda prototype:

- First PCBs beginning of 2011
- Quad silicon sensor
- Readout board with USB2







X-ray image of circuit board



Lambda project

Redesign of module ceramic:

- Not all "power" wire bond pads used
- Nonuniform pixel behaviour along chip, and some strange glitches
- Reason: voltage drop along the chip
- **•** redesigned ceramic board





Right-angled connection to readout



High-speed readout system

Common high-speed readout board developed by DESY

- 4 * 10 Gigabit Ethernet links available
- Large on-board RAM for burst operation
- Currently being tested

"Signal distribution" board connects to detector head

- Powering, DACs and ADCs, etc.
- Now being assembled





Cooling and vacuum operation

Germanium detector should operate about -70°C in vacuum

Ceramic PCB allows CTE matching and reasonable thermal conduction
<u>First tests have whole system in vacuum chamber</u>

Full systems will have vacuum barrier glued to SD board

First tests of vacuum barrier successful







Cooling and vacuum operation





Cooling and vacuum operation





- New sensor production
- Development of readout system and mechanics
- Ideas for TSV-compatible board development



Medipix3 TSV

- Existing 2 x 6 system could be modified for TSVs
 - Already using ceramic board to improve thermal match and cooling
 - Signal routing to BGA probably easier
 - Smaller sensors could be soldered to 2 x 6 module
- Could we build small modules (2 x 2)?
 - More flexible
 - Better yield of good modules
- Technical challenges
 - High speed readout >180 lines
 - Either multiple connectors or open pin field (less efficient)
 - Loss of wire bonding space makes fitting connectors and mechanics harder



Right-angle PCBs

Right-angle PCB

- Called: Wirelaid technic
- company: Jumatech (maybe others)
- Can be used for all FR4 PCBs
- ~ 1 line each 1-2 mm
- Could be used for powering
- differential pair routing impossible





Medipix3 TSV





Medipix3 TSV





Examples of 2 x 2 module connectors





Thanks for listening

